

NTF2955

Power MOSFET

-60 V, -2.6 A, Single P-Channel SOT-223

Features

- TMOS7 Design for low $R_{DS(on)}$
- Withstands High Energy in Avalanche and Commutation Modes
- Pb-Free Package is Available

Applications

- Power Supplies
- PWM Motor Control
- Converters
- Power Management

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-to-Source Voltage	V_{DSS}	-60	V	
Gate-to-Source Voltage	V_{GS}	± 20	V	
Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	I_D -2.6	A
		$T_A = 85^\circ\text{C}$	-2.0	
Power Dissipation (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	P_D 2.3	W
Continuous Drain Current (Note 2)	Steady State	$T_A = 25^\circ\text{C}$	I_D -1.7	A
		$T_A = 85^\circ\text{C}$	-1.3	
Power Dissipation (Note 2)		$T_A = 25^\circ\text{C}$	P_D 1.0	W
Pulsed Drain Current	$t_p = 10 \mu\text{s}$	I_{DM} -10.4	A	
Operating Junction and Storage Temperature	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$	
Single Pulse Drain-to-Source Avalanche Energy ($V_{DD} = 25 \text{ V}, V_G = 10 \text{ V}, I_{PK} = 6.7 \text{ A}, L = 10 \text{ mH}, R_G = 25 \Omega$)	EAS	225	mJ	
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)	T_L	260	$^\circ\text{C}$	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Tab (Drain) - Steady State (Note 2)	$R_{\theta JC}$	14	$^\circ\text{C/W}$
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	65	
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	150	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. When surface mounted to an FR4 board using 1 in. pad size (Cu. area = 1.127 in² [1 oz] including traces)
2. When surface mounted to an FR4 board using the minimum recommended pad size (Cu. area = 0.341 in²)

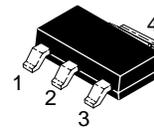
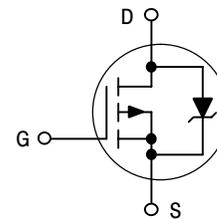


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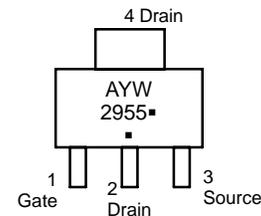
$V_{(BR)DSS}$	$R_{DS(on)}$ TYP	I_D MAX
-60 V	145 m Ω @ -10 V	-2.6 A

P-Channel



SOT-223
CASE 318E
STYLE 3

MARKING DIAGRAM AND PIN ASSIGNMENT



A = Assembly Location
Y = Year
W = Work Week
2955 = Device Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NTF2955T1	SOT-223	1000/Tape & Reel
NTF2955T1G	SOT-223 (Pb-Free)	1000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NTF2955

ELECTRICAL CHARACTERISTICS (T_J=25°C unless otherwise stated)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = -250 μA	-60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J			66.4		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = -60 V	T _J = 25°C		-1.0	μA
			T _J = 125°C		-50	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA

ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = -1.0 mA	-2.0		-4.0	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = -10 V, I _D = -0.75 A		145	170	mΩ
		V _{GS} = -10 V, I _D = -1.5 A		150	180	
		V _{GS} = -10 V, I _D = -2.4 A		154	185	
Forward Transconductance	g _{FS}	V _{GS} = -15 V, I _D = -0.75 A		1.77		S

CHARGES AND CAPACITANCES

Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = 25 V		492		pF
Output Capacitance	C _{OSS}			165		
Reverse Transfer Capacitance	C _{RSS}			50		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 30 V, I _D = 1.5 A		14.3		nC
Threshold Gate Charge	Q _{G(TH)}			1.2		
Gate-to-Source Charge	Q _{GS}			2.3		
Gate-to-Drain Charge	Q _{GD}			5.2		

SWITCHING CHARACTERISTICS (Note 4)

Turn-On Delay Time	t _{d(ON)}	V _{GS} = 10 V, V _{DD} = 25 V, I _D = 1.5 A, R _G = 9.1 Ω, R _L = 25 Ω		11		ns
Rise Time	t _r			7.6		
Turn-Off Delay Time	t _{d(OFF)}			65		
Fall Time	t _f			38		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 1.5 A	T _J = 25°C		-1.10	-1.30	V
			T _J = 125°C		-0.9		
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dI _S /dt = 100 A/μs, I _S = 1.5 A		36		ns	
Charge Time	t _a			20			
Discharge Time	t _b			16			
Reverse Recovery Charge	Q _{RR}			0.139		nC	

3. Pulse Test: pulse width ≤ 300μs, duty cycle ≤ 2%.

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES ($T_J = 25^\circ\text{C}$ unless otherwise noted)

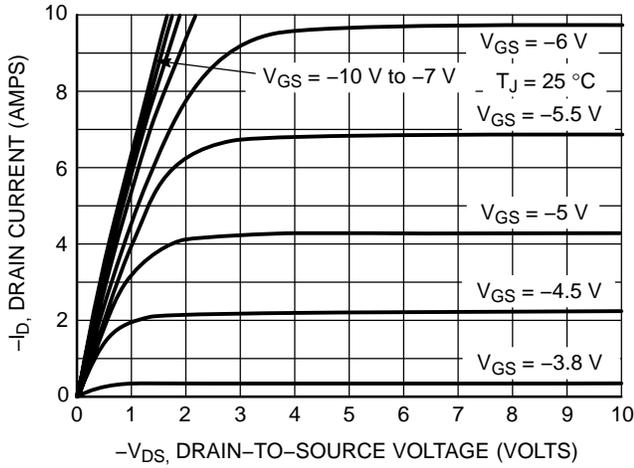


Figure 1. On-Region Characteristics

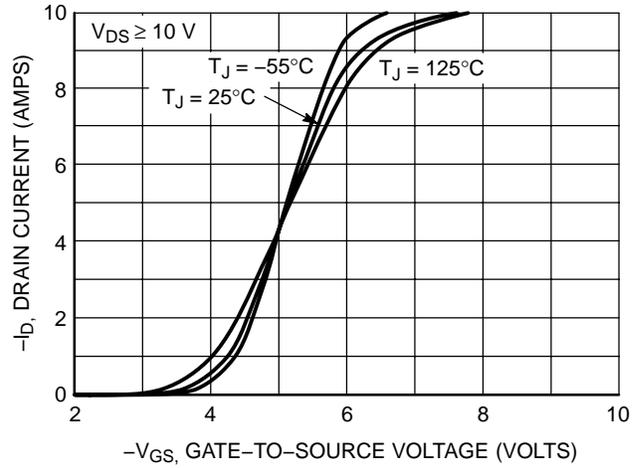


Figure 2. Transfer Characteristics

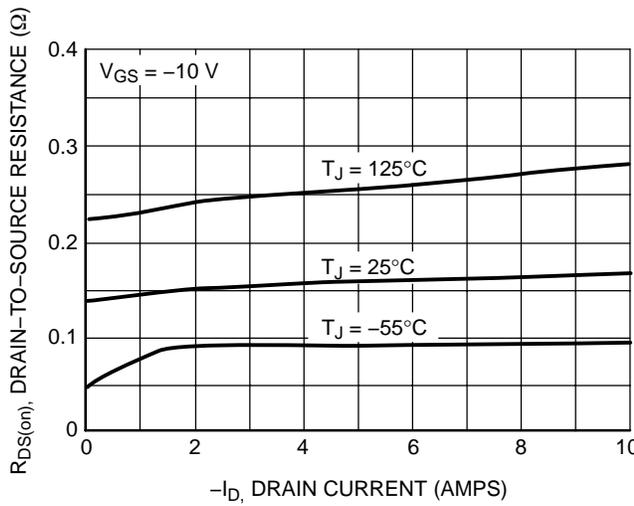


Figure 3. On-Resistance versus Drain Current and Temperature

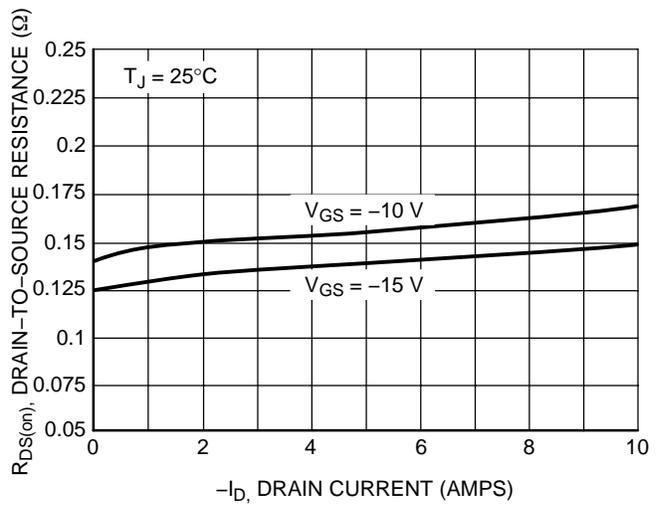


Figure 4. On-Resistance versus Drain Current and Gate Voltage

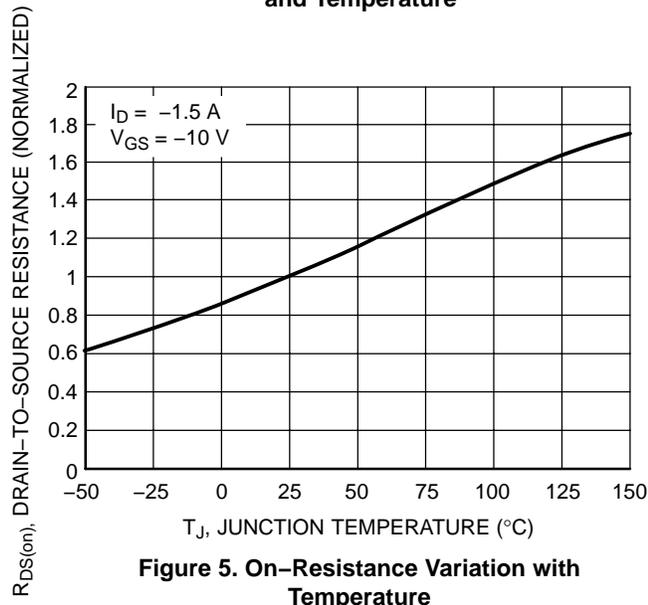


Figure 5. On-Resistance Variation with Temperature

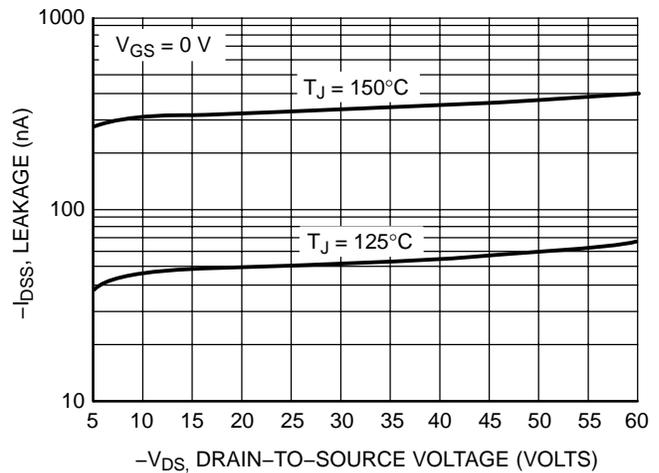


Figure 6. Drain-to-Source Leakage Current versus Voltage

TYPICAL PERFORMANCE CURVES ($T_J = 25^\circ\text{C}$ unless otherwise noted)

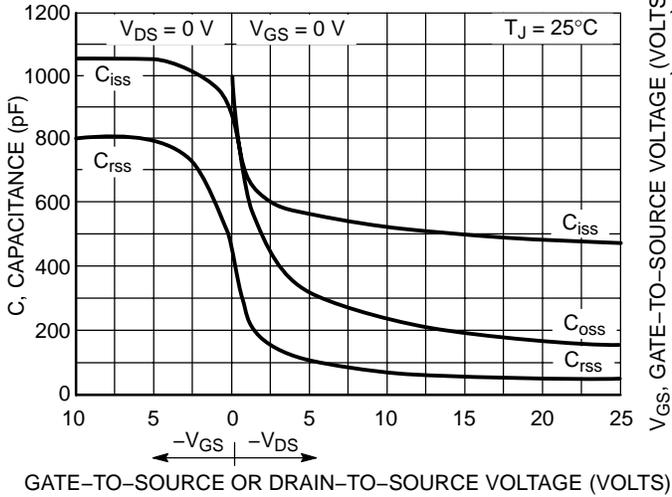


Figure 7. Capacitance Variation

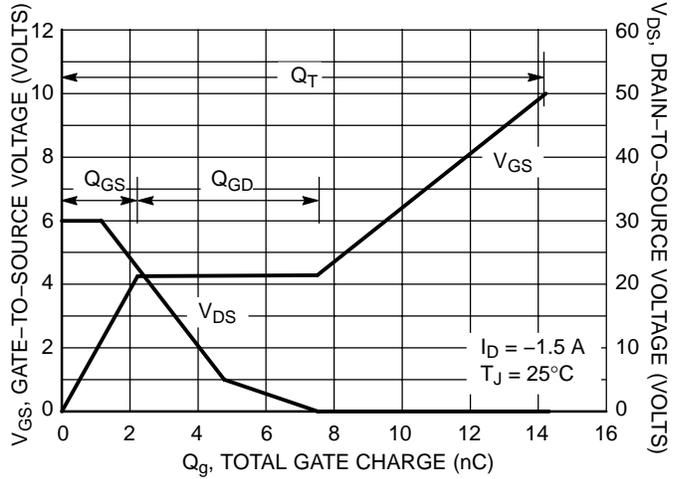


Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

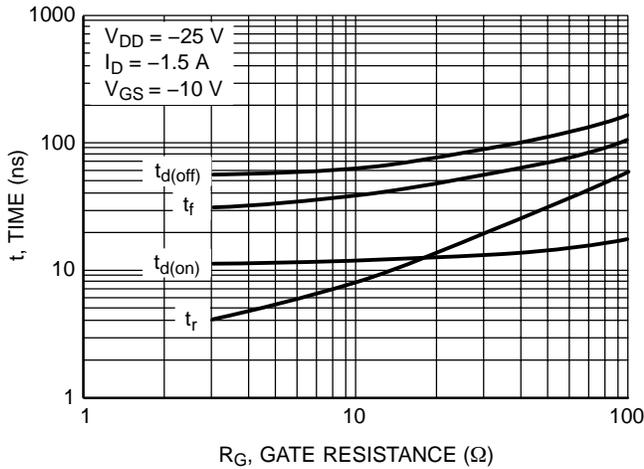


Figure 9. Resistive Switching Time Variation versus Gate Resistance

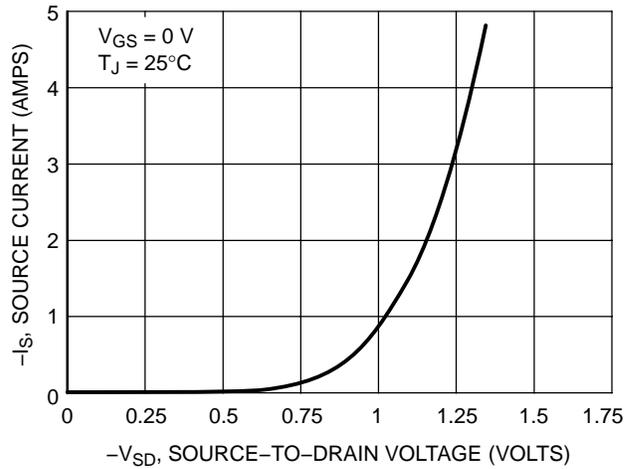


Figure 10. Diode Forward Voltage versus Current

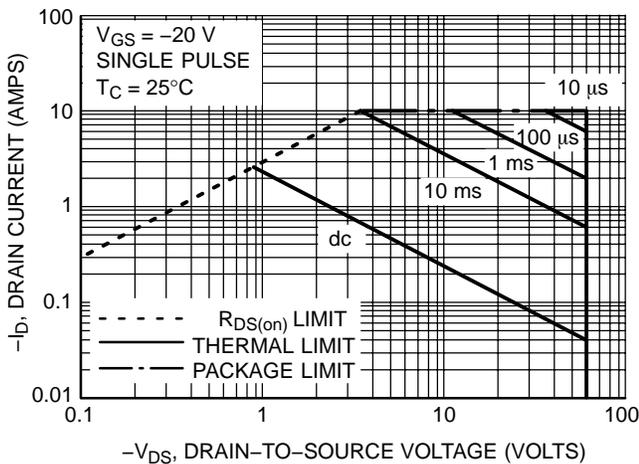


Figure 11. Maximum Rated Forward Biased Safe Operating Area

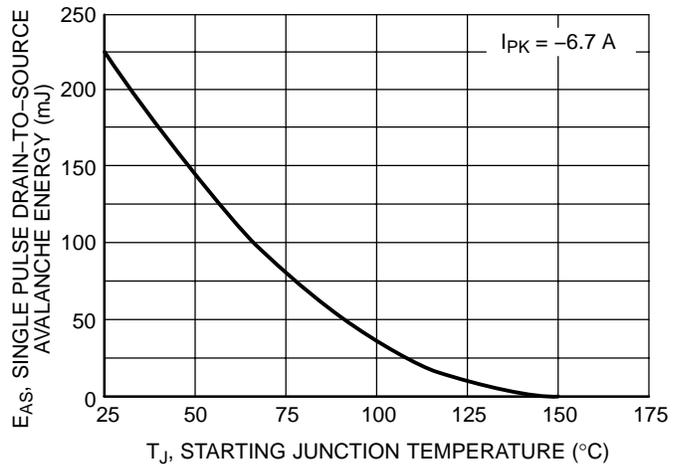
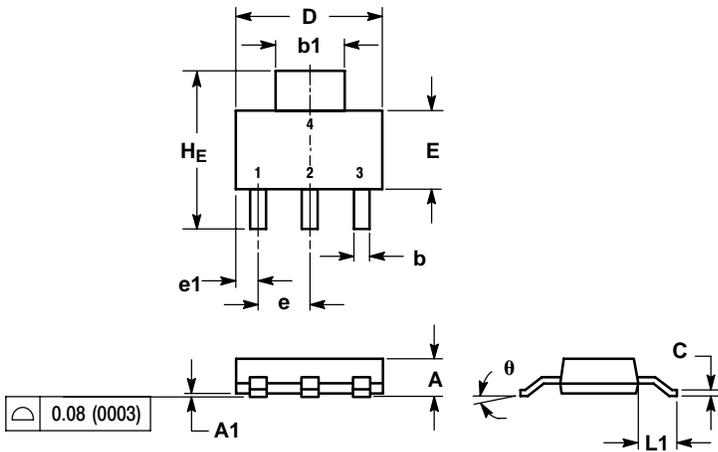


Figure 12. Maximum Avalanche Energy versus Starting Junction Temperature

NTF2955

PACKAGE DIMENSIONS

SOT-223 (TO-261)
CASE 318E-04
ISSUE L

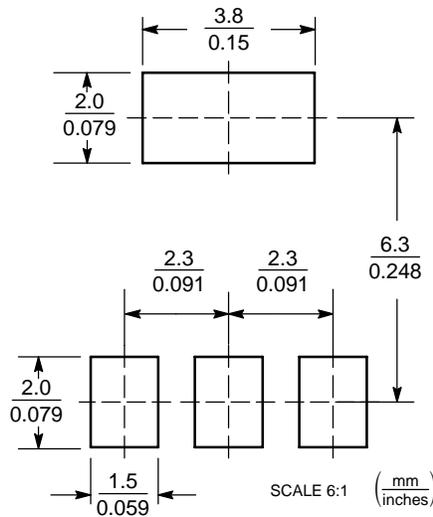


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
c	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
e	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

- STYLE 3:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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